



DA2J10400L

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Small reverse current IR
- Low terminal capacitance Ct
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol: C1

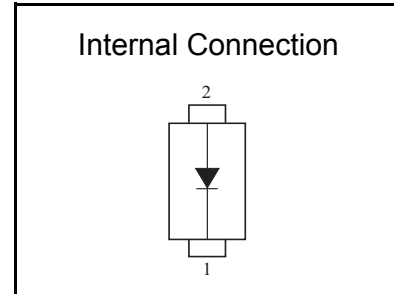
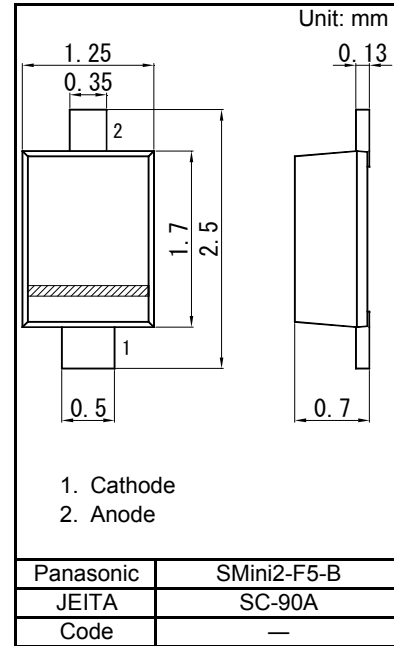
■ Packaging

Embossed type (Thermo-compression sealing) : 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	80	V
Maximum peak reverse voltage	VRM	80	V
Forward current	IF	200	mA
Peak forward current	IFM	600	mA
Non-repetitive peak forward surge current ^{*1}	IFSM	1	A
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note)*1: t = 1 s

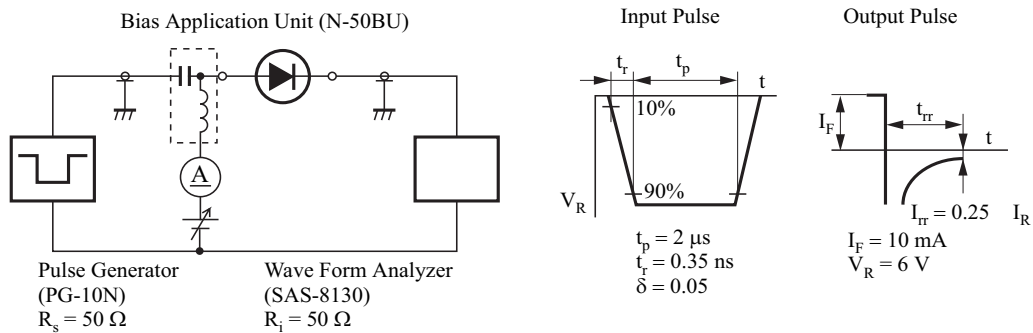




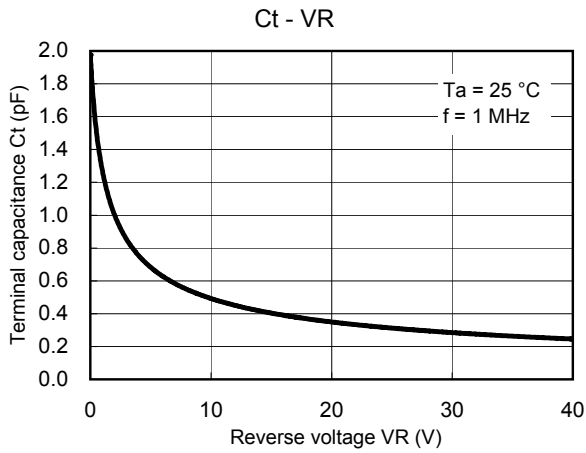
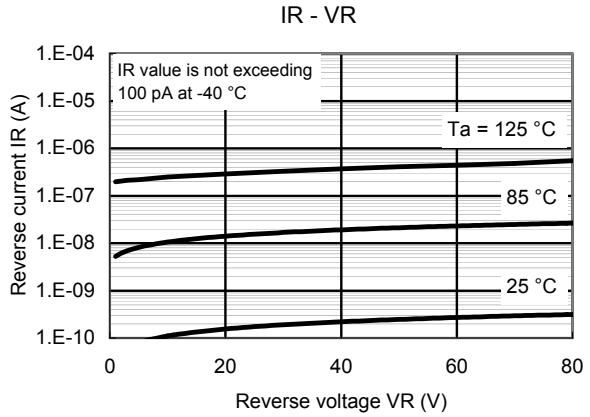
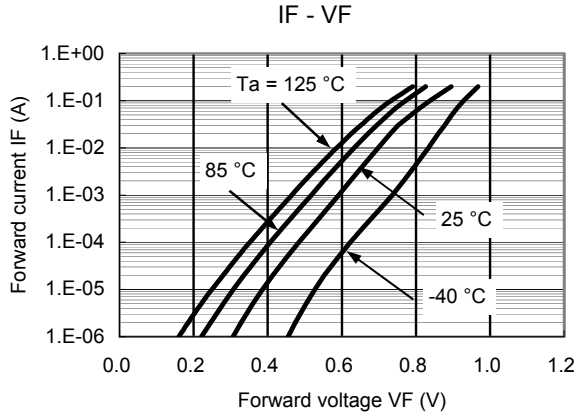
■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 200 mA		0.90	1.10	V
Reverse voltage	VR	IR = 100 μA	80			V
Reverse current	IR	VR = 80 V			500	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz			4	pF
Reverse recovery time *1	trr	IF = 10 mA, VR = 6 V Irr = 0.25 × IR			10	ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
 2. Absolute frequency of input and output is 100 MHz.
 3. *1: trr test circuit

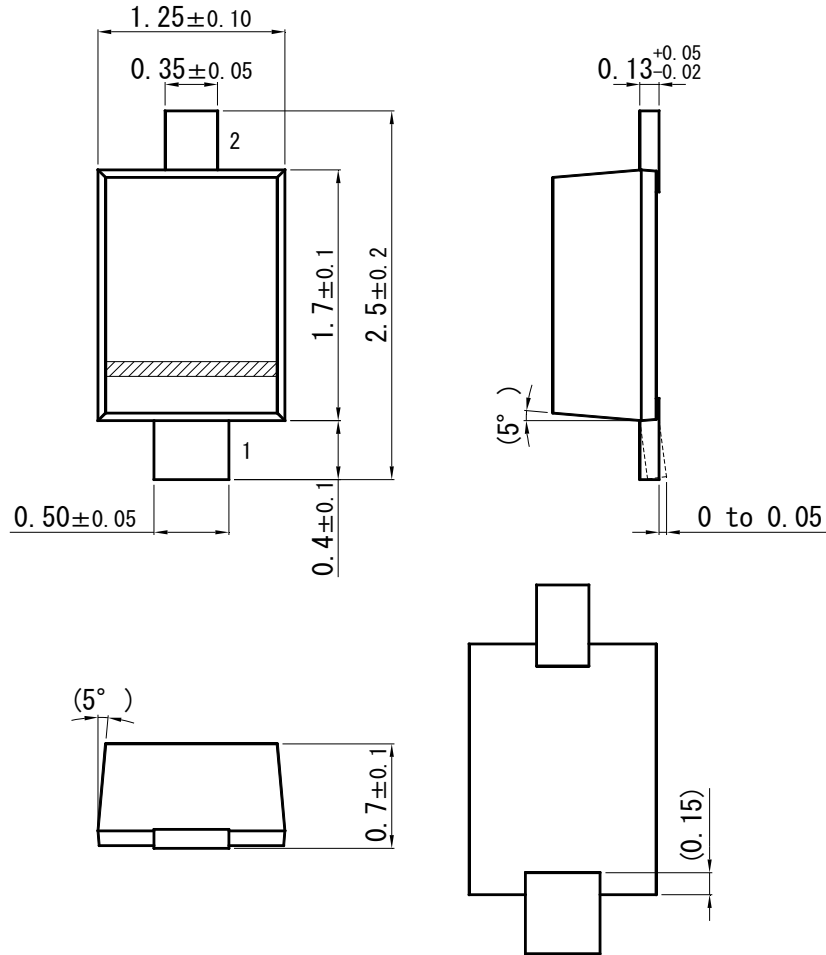


Technical Data (reference)

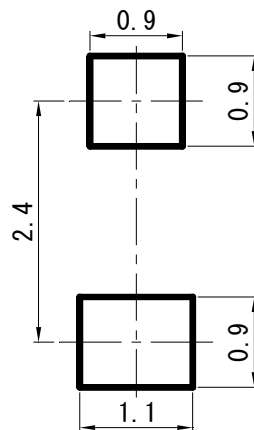


SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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